

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT2628664

SUBMISSION TYPE:	NEW ASSIGNMENT												
NATURE OF CONVEYANCE:	ASSIGNMENT												
CONVEYING PARTY DATA													
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>TUNG-YANG LIN</td> <td>11/19/2013</td> </tr> <tr> <td>HSIN-CHIH CHIANG</td> <td>11/19/2013</td> </tr> <tr> <td>RUEY-HSIN LIU</td> <td>11/17/2013</td> </tr> <tr> <td>MING-TA LEI</td> <td>11/19/2013</td> </tr> </tbody> </table>		Name	Execution Date	TUNG-YANG LIN	11/19/2013	HSIN-CHIH CHIANG	11/19/2013	RUEY-HSIN LIU	11/17/2013	MING-TA LEI	11/19/2013		
Name	Execution Date												
TUNG-YANG LIN	11/19/2013												
HSIN-CHIH CHIANG	11/19/2013												
RUEY-HSIN LIU	11/17/2013												
MING-TA LEI	11/19/2013												
RECEIVING PARTY DATA													
<table border="1"> <tr> <td>Name:</td> <td>TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.</td> </tr> <tr> <td>Street Address:</td> <td>NO. 8, LI-HSIN RD. VI</td> </tr> <tr> <td>Internal Address:</td> <td>HSINCHU SCIENCE PARK</td> </tr> <tr> <td>City:</td> <td>HSINCHU</td> </tr> <tr> <td>State/Country:</td> <td>TAIWAN</td> </tr> <tr> <td>Postal Code:</td> <td>300</td> </tr> </table>		Name:	TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.	Street Address:	NO. 8, LI-HSIN RD. VI	Internal Address:	HSINCHU SCIENCE PARK	City:	HSINCHU	State/Country:	TAIWAN	Postal Code:	300
Name:	TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.												
Street Address:	NO. 8, LI-HSIN RD. VI												
Internal Address:	HSINCHU SCIENCE PARK												
City:	HSINCHU												
State/Country:	TAIWAN												
Postal Code:	300												
PROPERTY NUMBERS Total: 1													
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>14089803</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	14089803								
Property Type	Number												
Application Number:	14089803												
CORRESPONDENCE DATA													
<p>Fax Number:</p> <p>Phone: 7036841111</p> <p>Email: tsmc@ipfirm.com</p> <p><i>Correspondence will be sent via US Mail when the email attempt is unsuccessful.</i></p> <p>Correspondent Name: LOWE HAUPTMAN & HAM, LLP (TSMC)</p> <p>Address Line 1: 2318 MILL ROAD</p> <p>Address Line 2: SUITE 1400</p> <p>Address Line 4: ALEXANDRIA, VIRGINIA 22314</p>													
ATTORNEY DOCKET NUMBER:	T5057-982												
NAME OF SUBMITTER:	RANDY A. NORANBROCK												

OP \$40.00 14089803

Signature:	/Randy A. Noranbrock/
Date:	11/26/2013
Total Attachments: 1 source=EfiledAssgn#page1.tif	

Docket No. T5057-982
TSMC2013-1317

ASSIGNMENT

In consideration of the premises and other good and valuable consideration in hand paid, the receipt and sufficiency of which is hereby acknowledged, the undersigned,

- 1) Tung-Yang LIN
- 2) Hsin-Chih CHIANG
- 3) Ruey-Hsin LIU
- 4) Ming-Ta LEI

who has made a certain new and useful invention, hereby sells, assigns and transfers unto TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD., having a place of business at No. 8, Li-Hsin Rd. VI, Hsinchu Science Park, Hsinchu 300, Taiwan R.O.C.,

its successors and assigns (hereinafter designated "ASSIGNEE") the entire right, title and interest for the United States of America as defined in 35 U.S.C. 100 in the invention entitled

SEMICONDUCTOR DEVICE HAVING DRAIN SIDE CONTACT THROUGH BURIED OXIDE

(a) for which an application for United States Letters Patent was filed on November 26, 2013, and identified by United States Patent Application No. 14/089,803; or

(b) for which an application for United States Letters Patent was executed on _____,

and the undersigned hereby authorizes and requests the United States Commissioner of Patents and Trademarks to issue any and all United States Letters Patent which may be granted therefore and any and all extensions, divisions, reissues, continuations, or continuations-in-part thereof, and the right to all benefits under the International Convention for the Protection of Industrial Property to the said ASSIGNEE, for its interest as ASSIGNEE, its successors, assigns and legal representatives; the undersigned agrees that the attorneys of record in said application shall hereafter act on behalf of said ASSIGNEE;

AND the undersigned hereby agrees to transfer a like interest, and to render all necessary assistance in making application for and obtaining original, divisional, reissued or extended Letters Patent of the United States, upon request of the said ASSIGNEE, its successors, assigns and legal representatives, and without further remuneration, in and to any improvements, and applications for patent based thereon, growing out of or related to the said invention; and to execute any papers by the said ASSIGNEE, its successors, assigns and legal representatives, deemed essential to ASSIGNEE's full protection and title in and to the invention hereby transferred.

SIGNED on the date indicated aside my signature:

1) Tung-Yang Lin
Name: Tung-Yang LIN

2013.11.19
Date:

2) Hsin-Chih Chiang
Name: Hsin-Chih CHIANG

2013.11.19
Date:

3) Ruey-Hsin Liu
Name: Ruey-Hsin LIU

2013.11.19
Date:

4) Ming-Ta Lei
Name: Ming-Ta LEI

2013.11.19
Date: